

N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

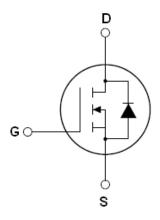
Features

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS}	650	V
R _{DS(ON) MAX}	180	mΩ
I_D	21	A



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65T180	TO-220	NCE65T180
NCE65T180F	TO-220F	NCE65T180F
NCE65T180D	TO-263	NCE65T180







Table 1. Absolute Maximum Ratings (T_c=25℃)

TO-263 TO-220 TO-220F

Parameter	Symbol	NCE65T180 NCE65T180D	NCE65T180F	Unit
Drain-Source Voltage (Vgs=0V)	V _{DS}	69	50	V
Gate-Source Voltage (V _{DS} =0V), AC (f>1 Hz)	V _G s	土	30	V
Continuous Drain Current at T _C =25°C	I _{D (DC)}	21	21*	Α
Continuous Drain Current at T _C =100°C	I _{D (DC)}	13.2	13.2*	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	84	84*	Α
Maximum Power Dissipation(T _C =25°C)	P _D	188	33.8	W
Derate above 25°C		1.5	0.27	w/°C
Single pulse avalanche energy (Note 2)	Eas	441		mJ
Avalanche current ^(Note 1)	I _{AR}	10.5		Α
Repetitive Avalanche energy , t_{AR} limited by T_{Jmax} (Note 1)	E _{AR}	0.7		mJ



Parameter	Symbol	NCE65T180 NCE65T180D	NCE65T180F	Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50		V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V}, I_{SD} < I_{D}$	dv/dt	1	5	V/ns
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55	+150	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE65T180 NCE65T180D	NCE65T180F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	0.66	3.69	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R_{thJA}	62.5	80	°C /W

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	, , , , , , , , , , , , , , , , , , ,		Min	Тур	Max	Unit
On/off states	,			<u> </u>		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V		0.05	1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250μA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10.5A		150	180	mΩ
Dynamic Characteristics	1				l .	
Forward Transconductance	g FS	V _{DS} = 20V, I _D = 10.5A		16		S
Input Capacitance	C _{lss}	\/ 50\/\\ 0\/		2250		PF
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V, F=1.0MHz		83		PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHZ		1.6		PF
Total Gate Charge	Q_g	V 400V/1 04A		36		nC
Gate-Source Charge	Q_{gs}	V _{DS} =480V,I _D =21A,		14		nC
Gate-Drain Charge	Q_{gd}	- V _{GS} =10V		8.5		nC
Switching times						
Turn-on Delay Time	t _{d(on)}			11		nS
Turn-on Rise Time	t _r	V _{DD} =380V,I _D =11A,		6		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=4\Omega,V_{GS}=10V$		61		nS
Turn-Off Fall Time	t _f			4.5		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T 0500			21	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	- T _C =25°C			84	Α
Forward on voltage	V_{SD}	T _j =25°C,I _{SD} =21A,V _{GS} =0V		0.9	1.3	V
Reverse Recovery Time	t _{rr}			310		nS
Reverse Recovery Charge	Qrr	T _j =25°C,I _F =21A,di/dt=100A/μs		5		uC
Peak Reverse Recovery Current	I _{rrm}			28		Α

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature

 $[\]textbf{2.} \ \, T_j\text{=}25\,^{\circ}\text{C}, V_{DD}\text{=}50\text{V}, V_G\text{=}10\text{V}, \, R_G\text{=}25\Omega$



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area for TO-220/TO-263

Figure 2. Safe operating area for TO-220F

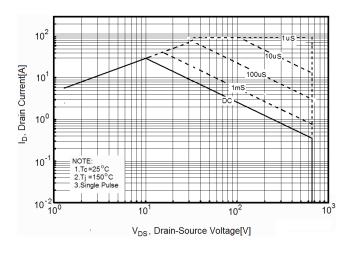


Figure 3. Source-Drain Diode Forward Voltage

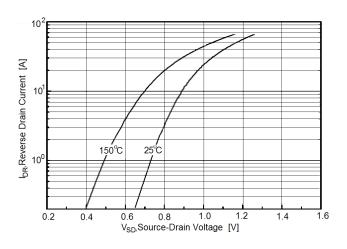
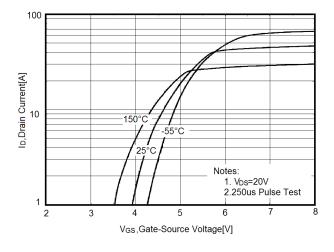


Figure 5. Transfer characteristics



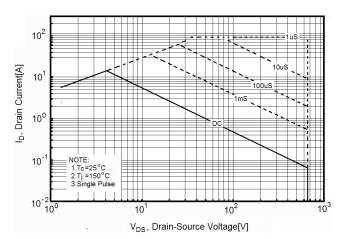


Figure 4. Output characteristics

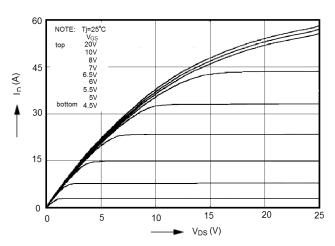


Figure 6. Static drain-source on resistance

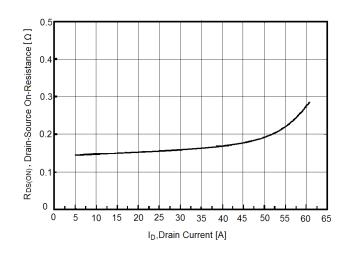




Figure 7. R_{DS(ON)} vs Junction Temperature

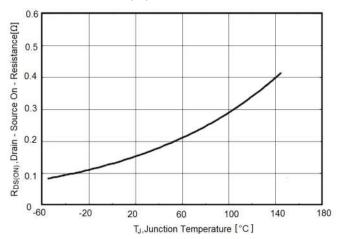


Figure 8. BV_{DSS} vs Junction Temperature

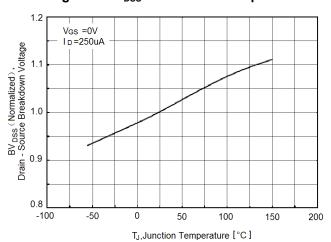


Figure 9. Maximum I_D vs Junction Temperature

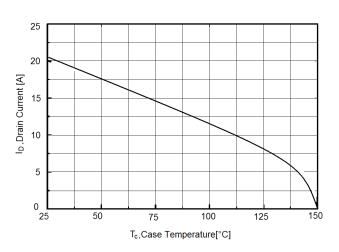


Figure 10. Transient Thermal Impedance for TO-220

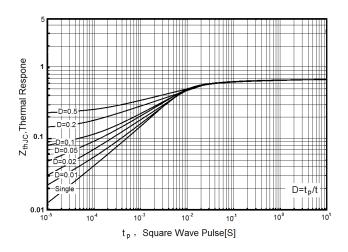


Figure 11. Transient Thermal Impedance for TO-220F

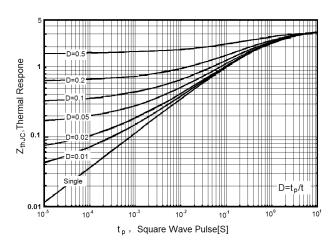


Figure 12. Gate charge waveforms

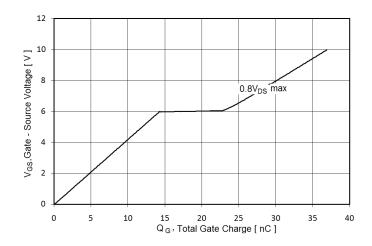
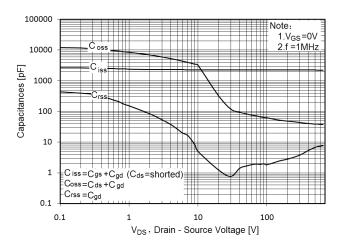




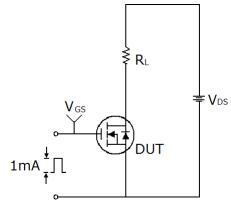
Figure 13. Capacitance

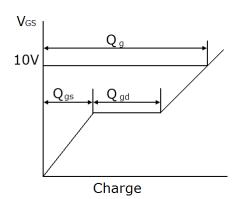




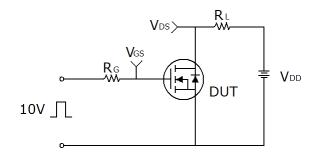
Test circuit

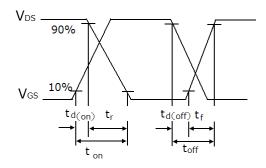
1) Gate charge test circuit & Waveform



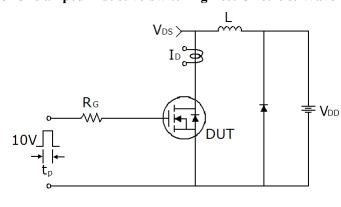


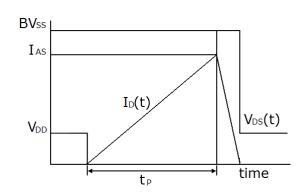
2) Switch Time Test Circuit:





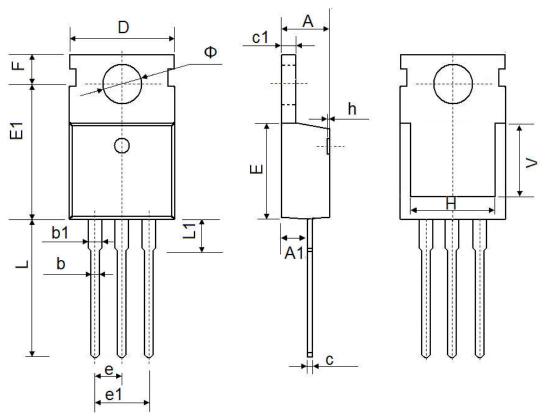
3) Unclamped Inductive Switching Test Circuit & Waveforms







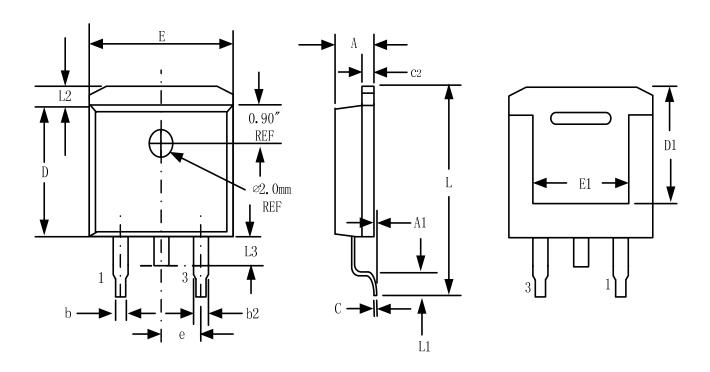
TO-220-3L-C Package Information



Complete al	Dimensions In Millimeters		Dimensions	s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
е	2.540 TYP.		0.100	TYP.
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500	REF.	0.295	REF.
Ф	3.400	3.800	0.134	0.150



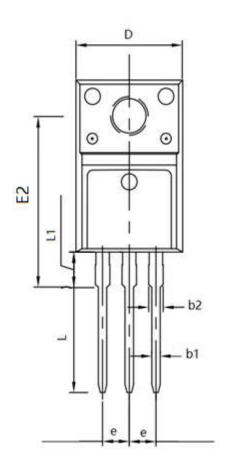
TO-263-3L Package Information

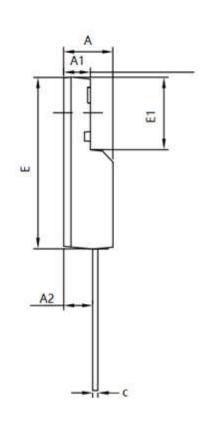


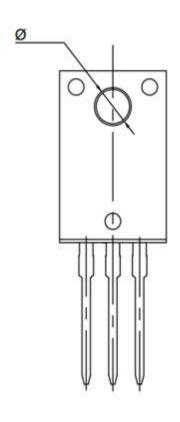
Sumb al	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.32	4.57	0.170	0.180	
A1	-	0.25		0.010	
b	0.71	0.94	0.028	0.037	
b2	1.15	1.40	0.045	0.055	
С	0.46	0.61	0.018	0.024	
c2	1.22	1.40	0.048	0.055	
D	8.89	9.40	0.350	0.370	
D1	8.01	8.23	0.315	0.324	
Е	10.04	10.28	0.395	0.405	
E1	7.88	8.08	0.310	0.318	
е	2.54	BSC	0.100	BSC	
L	14.73	15.75	0.580	0.620	
L1	2.29	2.79	0.090	0.110	
L2	1.15	1.39	0.045	0.055	
L3	1.27	1.77	0.050	0.070	



TO-220F Package Information







Symbol	Dimensions In Millimeters		Dimensions	In Inches
	Min.	Max.	Min.	Max.
A	4.500	4.900	0.177	0.193
A1	2.340	2.740	0.092	0.108
A2	2.560	2.960	0.101	0.117
b1	0.700	0.900	0.028	0.035
b2	1.180	1.580	0.046	0.062
С	0.400	0.600	0.016	0.024
D	9.960	10.360	0.392	0.408
E	15.670	15.970	0.617	0.629
E1	6.500	6.900	0.256	0.272
E2	15.500	16.100	0.610	0.634
е	2.540) TYP	0.100	TYP
Ф	3.080	3.280	0.121	0.129
L	12.640	13.240	0.498	0.521
L1	3.030	3.430	0.119	0.135



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